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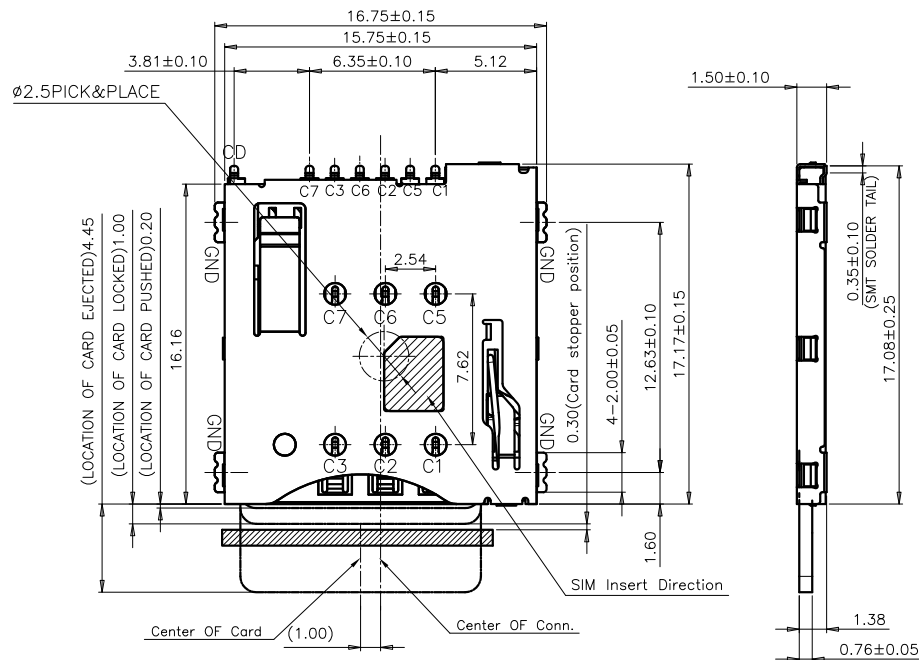
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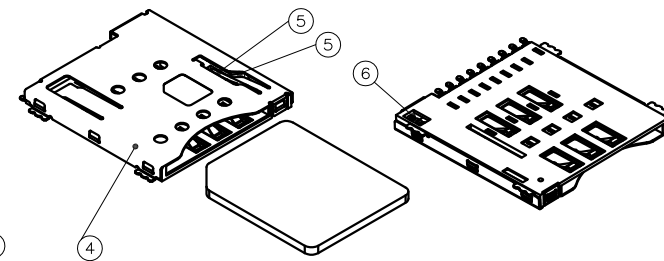
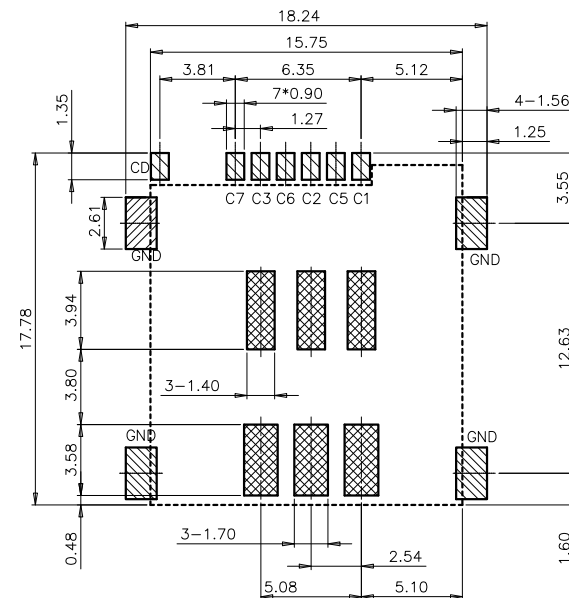
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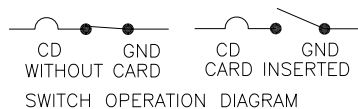
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
1	PROPOSE ONLY	ALLEN	2015.06.04



THIS AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES
SMT SOLDER AREA



ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN

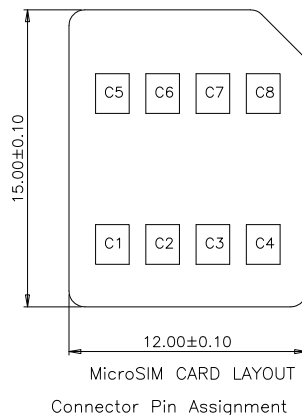


NOTES:

1. FINISH
1-1. CONTACT:
CONTACT AREA: Au 1~3u" Min.
GOLD FLASH PLATING ON SOLDER AREA
1-2. SHELL:
SOLDER AREA: Gold flash
2. ELECTRICAL REQUIREMENTS:
2-1. CURRENT RATING: 0.5A PER PIN.
2-2. CONTACT RESISTANCE: 50 mOhm MAX.
2-3. INSULATION RESISTANCE: 1000 MOhm MIN.200 VDC FOR 1 MINUTE.
2-4. WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.
3. MECHANICAL REQUIREMENTS:
DURABILITY: 3,000 CYCLES MIN.
4. ENVIRONMENT REQUIREMENTS:
4-1. OPERATING TEMP.: -30°C TO +85°C
4-2. STORAGE TEMPERATURE: -40°C TO +85°C
5. RECOMMENDED PROCESS DONDITION:
IR-REFLOW, PEAK TEMPERATURE AND TIME: 250°C, 5~10 S.

PART No.:

S 0 PP - 15 00 06- 17 G
SIM CON. G=gold plating
0=WITHOUT POST 17=Product Order
PP=PUSH Type Pin NO. 6=6Pin
15:HEIGHT 1.5mm 00=NORMAL TYPE.(ON PCB)



MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED MATAL MASK T=0.12MM
NO PATTERN AREA (TOLERANCE: ±0.05)

7	LINK	1PC	STEEL	PLATE WITH NICKEL
6	SPRING	1PC	SWP-B	PLATE WITH NICKEL
5	Slide	1PC	HI-TEMP THERMOPLASTIC	UL94V-0 BLACK
4	Shell	1PC	STEEL	SMT AREA :GOLD PLATED
3	CD Switch	1PC	COPPER ALLOY	CONTACT AREA:GOLD PLATED
2	Data Contact	6PC	COPPER ALLOY	CONTACT AREA:GOLD PLATED
1	Housing	1PC	HI-TEMP THERMOPLASTIC	UL94V-0 BLACK
NO	Description	Q'TY	Material	Color /plating
UNLESS OTHERWISE SPECIFIED TOLERANCES			深圳市精睿兴业科技有限公司 SHENZHEN KRCONN TECHNOLOGY CO., LTD	
DECIMALS:		ANGLES:	TITLE 1.5mm 6P Push Push Micro SIM CARD CONN.	
X	:±0.5	X	:±2°	DWN ALLEN PART NO. S0PP-150006-17G
X.X	:±0.20	X.X	:±1°	CHKD KEVIN SCALE:1:1 UNIT: mm
X.XX	:±0.10			APVD ERIC.W SIZE: A3 SHEET:1OF 1 REV: A1
CUSTOMER COPY				

